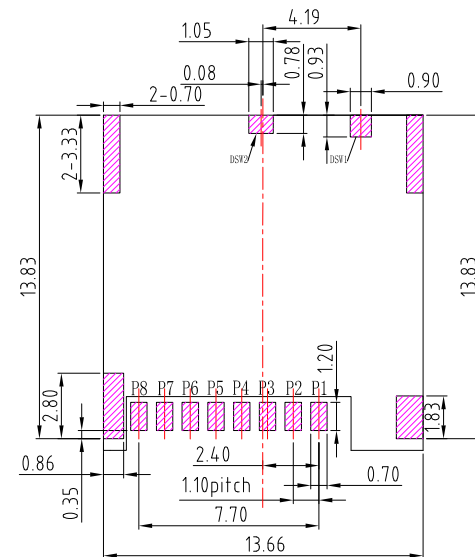
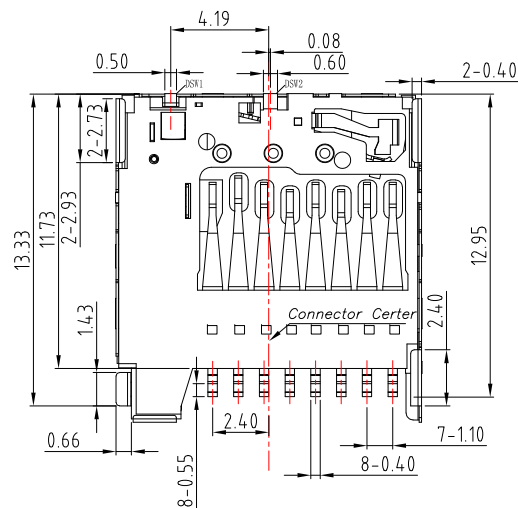
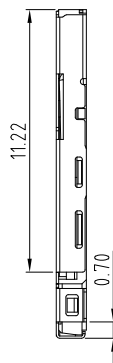
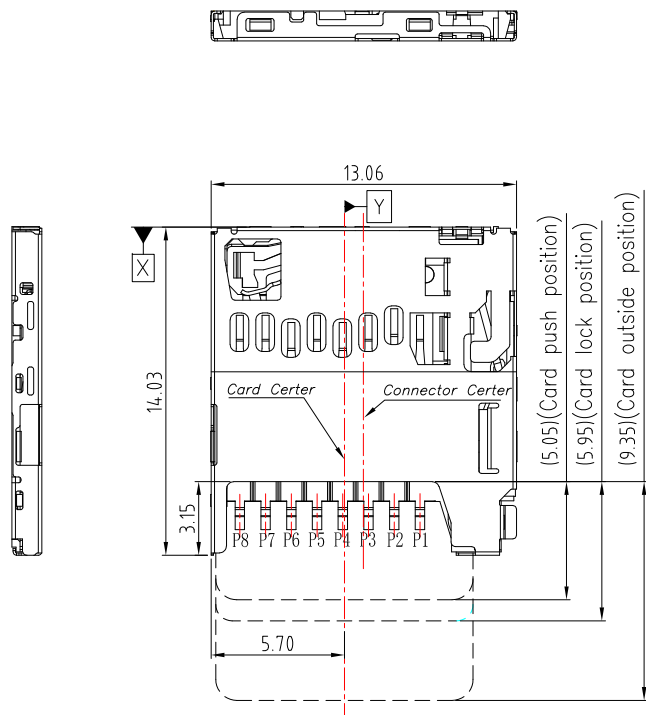
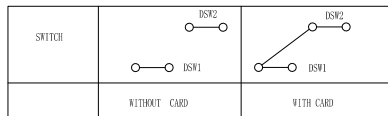
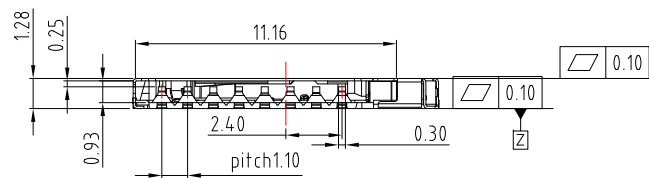




▨ PAD AREA
▨ KEEP OUT AREA
▨ GND PATTERN ONLY

PCB LAYOYT



PIN NO.	PIN ASSIGNMENT
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1

SPECIFICATION

Electrical :

- 1.Current Rating: 0.5A AC / DC Max
- 2.Voltage Rating: 12V AC / DC
- 3.Contact Resistance: 100 mΩ Max.
- 4.Insulation Resistance: 1000 MΩ Min.

Material:

- 1.Housing: LCP
- 2.Contact: Phosphor Bronze
- 3.Shell: SUS

Finish:

- 1.Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer

5	更新Contact材質	Jack	071724
4	更新樣式和材質	Jack	071624
3	更新PCB LAYOUT方向	Jack	012324
2	更新料號	Jack	112421
1	更新料號	Jack	112321
ITEM NO.	DESCRIPTION	DRAWN	DATE

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°
3RD. ANGEL'S
UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	07/17/24	FINISH	MODLE	MICRO SD CARD PUSH PUSH H1.28
CHECKED BY:	DATE	SCALE	DWG NO.	SD-TF128-S267
Jacky Chen	07/17/24	1 : 1	PART NO.	SD-TF128-S267
APPROVED BY:	DATE	SHEET NO.	1 of 1	VER R6
Tony Kao	07/17/24			